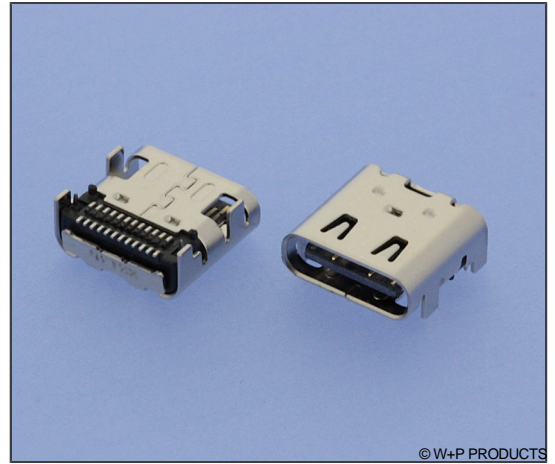
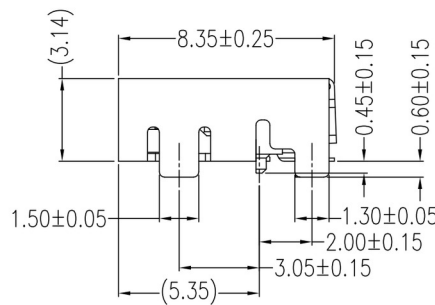
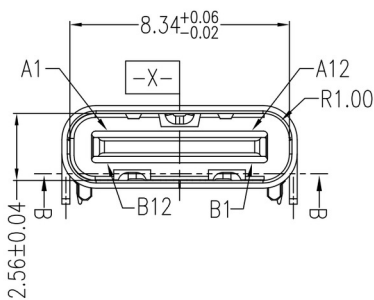
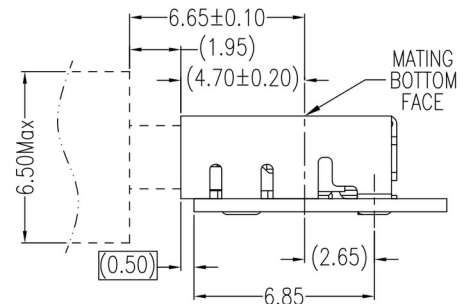
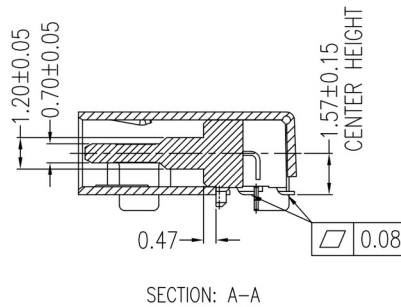
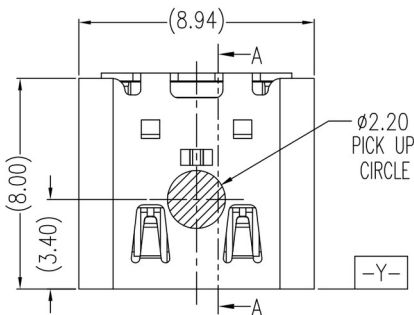


Technische Daten / Technical Data

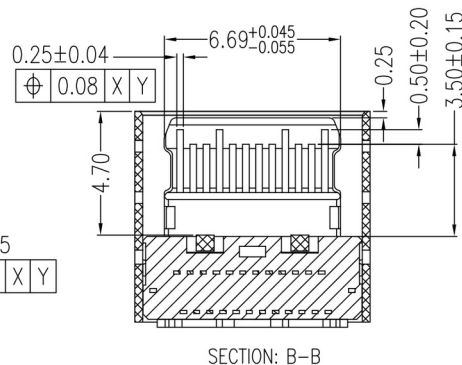
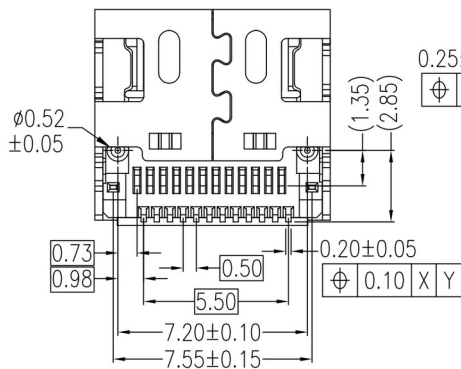
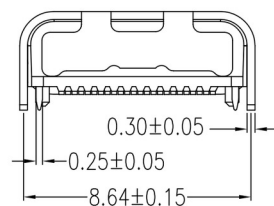
Gehäuse	Stahl vernickelt
Shell	Steel, nickel plated
Isolierkörper	Thermoplast, nach UL94 V-0
Insulator	Thermoplastic, rated UL94 V-0
Kontaktmaterial	Kupferlegierung
Contact Material	Copper alloy
Kontaktoberfläche	Au 30µ" über Ni
Contact Surface	Au 30µ" over Ni
Oberfläche Lötanschluss	Sn über Ni
Plating Solder Side	Sn over Ni
Durchgangswiderstand	< 40 mΩ
Contact Resistance	< 40 mΩ
Isolationswiderstand	> 100 MΩ
Insulation Resistance	> 100 MΩ
Spannungsfestigkeit	100 V AC
Test Voltage	100 V AC
Nennspannung	20 V
Voltage Rating	20 V
Nennstrom	5 A VBUS, 1,25 A VCONN
Current Rating	5 A VBUS, 1,25 A VCONN
Temperaturbereich	-55 °C ... +85 °C
Temperature Range	-55 °C ... +85 °C
Verarbeitung	Reflow-Lötverfahren 260 °C / 10sec
Processing	Reflow soldering 260 °C / 10sec



© W+P PRODUCTS



MATED CONDITION (REF.)



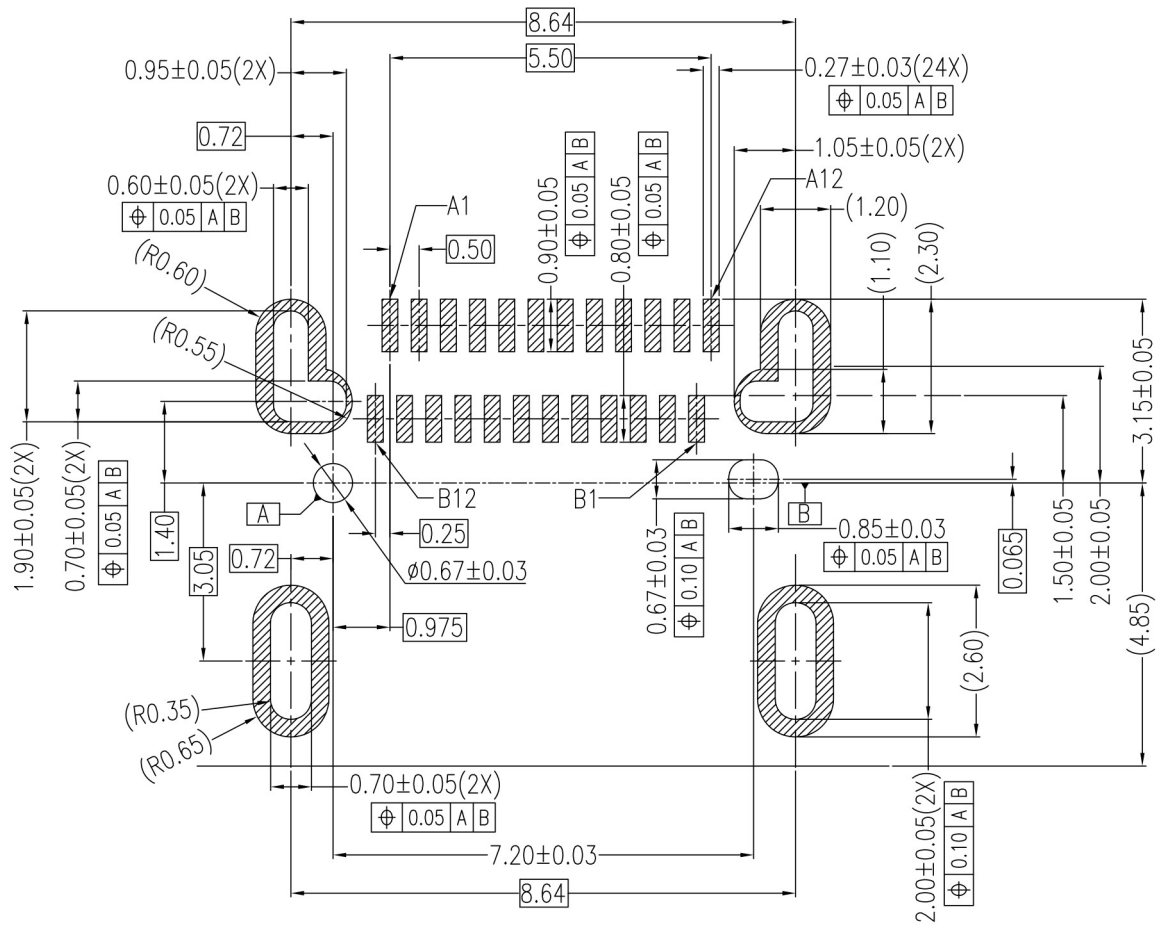
PIN ASSIGNMENT:

Pin No.	Signal Name	Pin No.	Signal Name
A1	GND	B12	GND
A2	SSTXp1	B11	SSRXp1
A3	SSTXn1	B10	SSRXn1
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU2
A6	Dp1	B7	Dn2
A7	Dn1	B6	Dp2
A8	SBU1	B5	CC2
A9	VBUS	B4	VBUS
A10	SSRXn2	B3	SSTXn2
A11	SSRXp2	B2	SSTXp2
A12	GND	B1	GND

8340-1

USB 4 Typ C SMT-Steckverbinder, horizontal

USB 4 Type C SMT-Connector, horizontal



P.C.B. LAYOUT(T=0.80mm)(For PIP)

COMPONENT SIDE

Series

8340

Version

1

1 CL = 1.57mm

Type

2

2 Liegend
Horizontal

Plating

80

80 Sel. Au 0.75µm / Sn

Packing

TR

TR Tape & Reel

Informationen zum kurzen Reflow-Lötverfahren

Fast Profile Reflow Soldering Information

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150°C
Temperatur Maximum T_{Smax}	200°C
Dauer $T_{Smin} - T_{Smax}$	120-150s
Temperatur Lötbereich T_L	230°C
Verweildauer oberhalb T_L	60s max.
Ramp-Up Rate $T_{Smax} - T_P$	max. 1,5°C / s
Höchsttemperatur T_P	260°C max.
Dauer Höchsttemperatur	5-10s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	3°C / s
Dauer 25°C - Höchsttemperatur T_P	Max. 4,5min

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150°C
Maximum Temperatur T_{Smax}	200°C
Duration $T_{Smin} - T_{Smax}$	120-150s
Soldering Range Temperature T_L	230°C
Duration above T_L	60s max.
Ramp-Up Rate $T_{Smax} - T_P$	max. 1.5°C / s
Peak Temperature T_P	260°C max.
Duration Peak Temperature	5-10s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	3°C / s
Duration 25°C - Peak Temp. T_P	Max. 4.5min

